TOSHIBA PHOTOCOUPLER GaAs IRED & PHOTO-TRIAC

# TLP3021(S),TLP3022(S),TLP3023(S)

OFFICE MACHINE
HOUSEHOLD USE EQUIPMENT
TRIAC DRIVER
SOLID STATE RELAY

The TOSHIBA TLP3021 (S), TLP3022 (S) and TLP3023 (S) consist of photo-triac optically coupled to a gallium arsenide infrared emitting diode in a six lead plastic DIP.

• Peak Off-State Voltage : 400 V (min)

• Trigger LED Current : 15 mA (max) (TLP3021(S))

10 mA (max) (TLP3022(S)) 5 mA (max) (TLP3023(S))

On-State Current : 100 mA (max)
 Isolation Voltage : 5000Vrms(Min)

• UL Recognized : UL1577,File No.E67349

• SEMKO Approved : SS EN60065

SS EN60950, File No.9841105

BSI Approved : BS EN60065, File No.8385

BS EN60950, File No.8386

• Option (D4) type

VDE approved: DIN EN60747-5-2

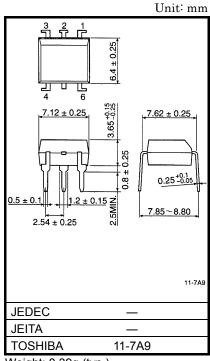
Approved No. 40009302

Maximum operating insulation voltage: 890 VpK Highest permissible over voltage: 8000 VpK

(Note):When a EN60747-5-2 approved type is needed, please designate the "Option (D4)"

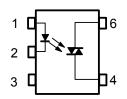
#### • Construction Mechanical Rating

	7.62 mm pich Standard Type	10.16 mm pich TLPxxxxF Type		
Creepage Distance	7.0 mm (Min)	8.0 mm (Min)		
Clearance	7.0 mm (Min)	8.0 mm (Min)		
Insulation Thickness	0.5 mm (Min)	0.5 mm (Min)		



Weight: 0.39g (typ.)

# Pin Configuration (top view)



- 1: Anode
- 2: Csthode
- 3: N.C.
- 4:Terminal 1
- 6:Terminal 2



### **Absolute Maximum Ratings (Ta=25°C)**

	CHARACTERISTIC		SYMBOL	RATING	UNIT	
LED	Forward Current	l <sub>F</sub>	50	mA		
	Forward Current Derating (Ta≥53°C)	ΔI <sub>F</sub> /°C	-0.7	mA /°C		
	Peak Forward Current (100µs pulse, 100pps)	IFP	1	Α		
۳	Power Dissipation		$P_D$	100	mW	
	Power Dissipation Derating (Ta≥25°C)		ΔP <sub>D</sub> /°C	-1.0	mW/°C	
	Reverse Voltage		V <sub>R</sub>	5	V	
	Junction Temperature	Tj	125	°C		
	Off-State Output Terminal Voltage	$V_{DRM}$	400	V		
	On-State RMS Current	Ta=25°C	l	100	mA	
	On-State Rivis Guilent	Ta=70°C	I <sub>T(RMS)</sub>	50		
OR.	On-State Current Derating (Ta≥25°C)	ΔI <sub>T</sub> /°C	-1.1	mA /°C		
DETECTOR	Peak On-State Current (100µs pulse, 120pps)	I <sub>TP</sub>	2	Α		
DEI	Peak Nonrepetitive Surge Current (Pw=10ms)	I <sub>TSM</sub>	1.2	Α		
	Power Dissipation	P <sub>D</sub>	300	mW		
	Power Dissipation Derating (Ta≥25°C)	ΔP <sub>D</sub> /°C	-4.0	mW/°C		
	Junction Temperature	Tj	115	°C		
Stor	rage Temperature Range	T <sub>stg</sub>	-55 to 150	°C		
Оре	erating Temperature Range	T <sub>opr</sub>	-40 to 100	°C		
Lea	Lead Soldering Temperature (10s)			260	°C	
Tota	Total Package Power Dissipation			330	mW	
Tota	Total Package Power Dissipation Derating (Ta≥25°C)			-4.4	mW /°C	
Isola	ation Voltage (AC,1min. , R.H.≤60%)	BVS	5000	Vrms		

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

(Note 2) Device considered a two terminal device :Pins1,2 and 3 shorted together and pin4 and pin6 shorted together.

### **Recommended Operating Conditions**

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply Voltage	V <sub>AC</sub>	_	_	120	$V_{\text{ac}}$
Forward Current	l <sub>F</sub> *	15	20	25	mA
Peak On-State Current	I <sub>TP</sub>	_	_	1	Α
Operating Temperature	T <sub>opr</sub>	-25	_	85	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

<sup>\*</sup>In The case of TLP3022



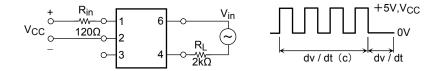
## Individual Electrical Characteristics (Ta=25°C)

CHARACTERISTIC SYMBOL		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
	Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 10 mA	1.0	1.15	1.3	V
LED	Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 5 V	_	_	10	μA
	Capacitance	C <sub>T</sub>	V = 0, f=1MHz	_	10	_	pF
22	Peak Off-State Current	I <sub>DRM</sub>	V <sub>DRM</sub> =400V	_	10	1000	nA
0 1	Peak On-State Voltage	$V_{TM}$	I <sub>TM</sub> =100mA	_	1.7	3.0	V
ပ	Holding Current	lΗ	_	_	0.6	_	mA
ΗE	Critical Rate of Rise of Off-State Voltage	dv/dt	Vin=120Vrms , Ta=85°C (Fig.1)	200	500	_	V/µs
D E	Critical Rate of Rise of Commutating Voltage	dv/dt(c)	Vin=30Vrms , IT=15mA (Fig.1)	_	0.2	_	V/µs

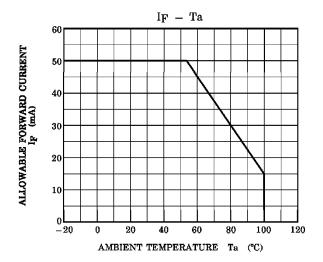
## **Coupled Electrical Characteristics (Ta=25°C)**

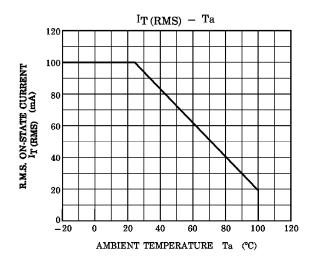
CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Trigger LED Current	TLP3021(S)	I <sub>FT</sub>	V <sub>T</sub> =3V	_	_	15	mA
	TLP3022(S)			_	5	10	
	TLP3023(S)			_	_	5	
Capacitance (Input to Output)		Cs	VS=0 , f=1MHz	_	0.8	_	pF
Isolation Resistance		Rs	VS=500V(R.H.≤60%)	5×10 <sup>10</sup>	10 <sup>14</sup>	_	Ω
			AC , 1minute	5000	_	_	Vrms
Isolation Voltage		$BV_S$	AC , 1second,in oil	_	10000	_	VIIIIS
			DC , 1minute,in oil		10000	_	Vdc

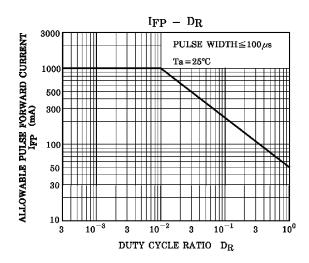
Fig. 1 dv / dt test circuit

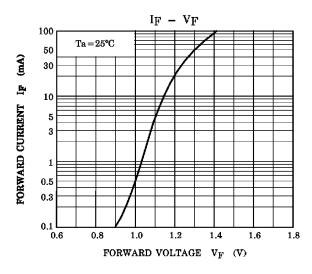


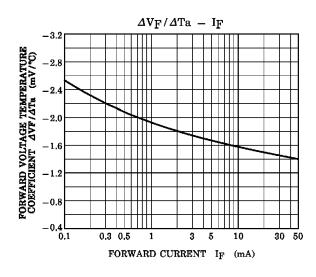
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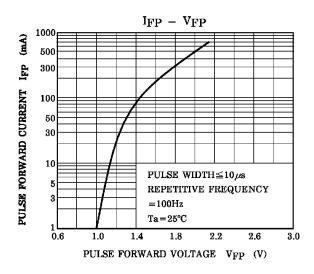




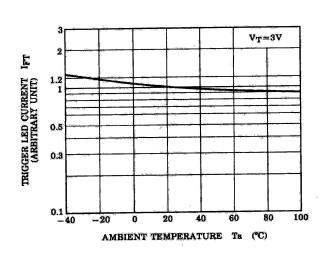




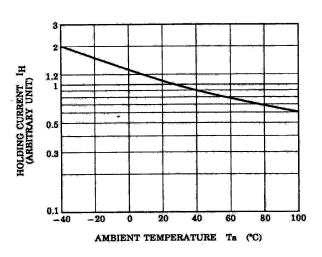




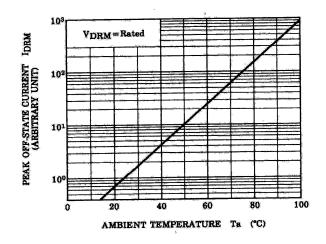
NORMALIZED IFT - Ta



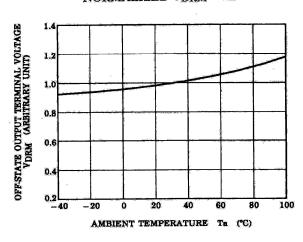
NORMALIZED IH - Ta



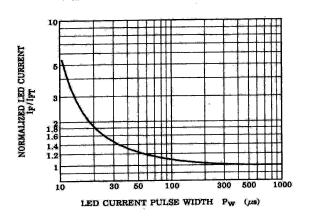
NORMALIZED IDRM - Ta



NORMALIZED VDRM - Ta



NORMALIZED LED CURRENT - LED CURRENT PULSE WIDTH





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